



**IAC-IMX8MM-Kit Embedded Development Kit**

**Hardware Manual**

Version: V 2.0  
2020.04

**ZHEJIANG QIYANG INTELLIGENT TECHNOLOGY Co., Ltd**  
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## Version Update

Version	Hardware	Description	Date	Reviser
1.0	IAC-IMX8MM-MB V1.00	Internal version	2020-02	wangwx
1.2	IAC-IMX8MM-MB V1.10	Update wireframe pictures	2020-04	wwx
2.0	IAC-IMX8MM-MB V1.20	Update pictures	2020-06	wwx



Note: This manual mainly introduces the hardware interfaces of the development board. ....4

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Note: This manual mainly introduces the hardware interfaces of the development board.

## I. Preface

### 1.1 Company Profile:

Zhejiang Qiyang Intelligent Technology Co., Ltd. Was established in Hangzhou in 2007. It is a National High-tech Enterprise focusing on the development, production and sales of ARM embedded products. More than 10 years of accumulation and precipitation have successfully constructed a service chain from product development to mass production.

As the core of the company, Qiyang R&D team is composed of more than 30 embedded engineers, who committed to providing users with easy-to-use embedded hardware, software tools and customized product solutions. Our products and solutions have been widely used in industrial control, Internet of Things, new retail, medical, electricity, environmental monitoring, charging piles and other fields.

The production base established in Zhuji provides a strong guarantee for Qiyang. It covers a over 5,000 square meters area also has 2 SMT production lines, and has passed and strictly followed the ISO9001 quality management system certification to guide production. With the strong production strength, the annual output can reach 1 million sets, ensuring the delivery time and solving the worries of users.

Qiyang has a complete sales market network, professional sales and after-sales

team providing users with a full range of technical support and services. The business has spread to more than 120 countries and regions, and has successfully helped more than 2,000 users to quickly and efficiently bring products to the market.

The combination and extension of R&D, production capacity and market has laid a solid foundation for Qiyang to become a professional and global supplier of embedded software and hardware.

We offer:

- **Multi-platform software/hardware products**

NXP, Rockchip, MTK, Renesas, TI, Atmel, Cirrus Logic and other multi-platform ARM development boards/core boards/industrial control boards and peripheral hardware products, as well as supporting tools and software resources to support users' rapid secondary development.

- **Customized service**

Give full play to the accumulation of technology on the ARM platform, Linux, Android, and Ubuntu operating systems to provide users with customized embedded product services (OEM/ODM).

Thank you for using Qiyang Intelligent products. We will spare no effort on providing you with technical assistance! Wish you success in your work!

## 1.2、IAC-IMX8MM-KIT Development board

1. Please read the instructions first before using the development board;

2. Please check the packing list and see whether there is a missing file in the CD before using the development board;
3. Please understand the basic structure and composition of IAC-IMX8MM-KIT, including the allocation of hardware resource, the definition of each pin of the core and bottom board, and the definition of extended pins, etc..
4. If you need to design and develop under the Linux system and burn program into the development board. Besides the document, we also suggest reading another document, IAC-IMX8MM-KIT Linux User Manual;
5. If you need to design and develop under the Android system and burn program into the development board. Besides the document, we also suggest reading another document, IAC-IMX8MM-KIT Linux User Manual;
6. IAC-IMX8MM-KIT embedded development board accept batch order.

## **II. System Composition**

### **2.1 Chip Summary**

The IAC-IMX8MM-KIT embedded development board adopts the i.MX8M Mini series application processor. The i.MX 8M Mini application processor is an NXP product that can bring the latest video and audio experience, with the most advanced specific media functions, using high-performance processing technology, while optimizing power consumption. The i.MX8M Mini series processors use an

advanced quad-core Arm®Cortex®-A53 core, which runs at speeds up to 1.8 GHz. And a general-purpose Cortex®-M4 400 MHz core processor is used for low-power processing. The DRAM controller supports 32-bit/16-bit LPDDR4, DDR4 and DDR3L memories. Besides, a variety of audio interfaces are available, including I2S, AC97, TDM and S/PDIF.

The functional block diagram of the processor is as follows:

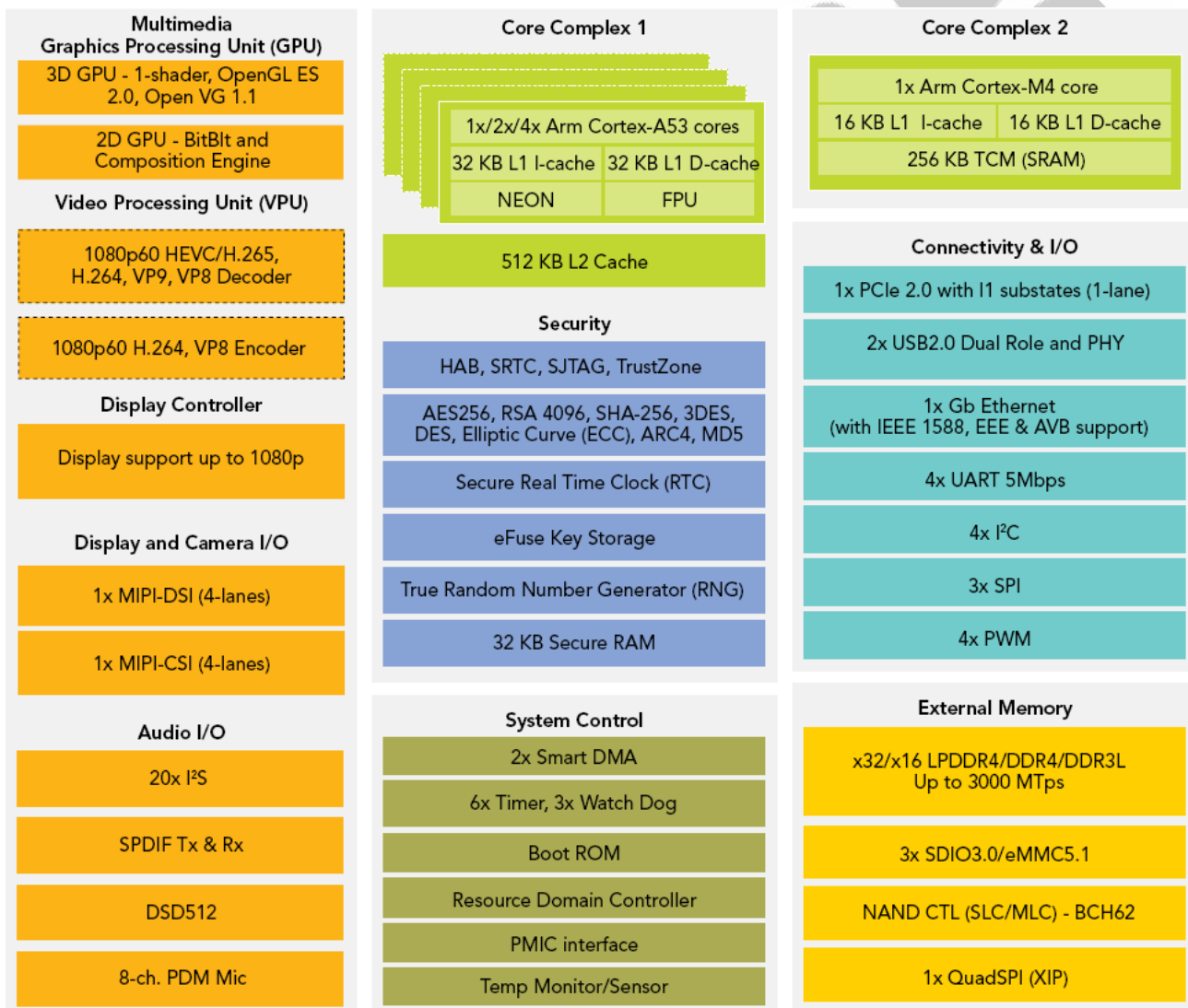


Chart 1



◆Multi-core Processing:

4 Cortex-A53, running up to 1.8GHz per core, support 32KB L1-I cache/ 32 kB L1-D cache /512 kB L2 cache, MPE with NEON, support advanced single instruction multiple data (SIMP) architecture, support 64 bits ARM8-A architecture, support VFPv4-d16 FPU.

1 Cortex-M4, running up to 400MHz, with 16 kB L1-I cache/ 16 kB L2-D cache/256kB TCM

◆GPU:

3D GPU (1\* mental ray, OpenGL® ES 2.0 )

2D GPU

◆ Display interface: 1-ch MIPI DSI (4 channel) with PHY

◆ Video Display: support 1080p60 VP9 Profile 0, 2 (10bits)decoding, HEVC/H.265 decoding, AVC/H.264, Main,advanced decoding, VP8 decoding, 1080p60 AVC/H.264 encoding, VP8 encoding.

◆ Audio: support 5-chSAI, 8\*PDM input

◆ Camera interface: 1-ch MIPI CSI (4 channel) with PHY

◆ USB:2-ch USB 2.0 with PHY

◆ PCIe: 1-ch PCIe 2.0 (1-ch ), with L1 low power consumption sub-state

◆ Ethernet: 1-ch Gigabit Ethernet (MAC) with AVB and IEEE 1588 (EEE stands for Energy Efficient Ethernet which applies to low-power consumption equipment.)

◆ Three uSDHC interface:

MMC 5.1 accord to HS400 DDR, supporting up to 400 MB/sec speed rate.

SD/SDIO 3.0 accord to 200 MHz SDR, supporting up up 100 MB/sec speed rate

Support SDXC (expandable)

◆ In-chip Storage:lead:boot ROM( 256kB), in-chip RAM (256kB+32kB)

◆ EMIFA:

32/16 bit DRAM interface supports LPDDR4 ( up to 2.5GHz)/ DRR4-2400/DDR3L-1600

Support 8 bits NAND Flas, including Raw MLC/SLC, more than 62 bits BCHECC according to ONFi 3.2

(Clock rate reaches 100MHz, Data transmission rate achieves 200MB/sec)

Support eMMc5.1 Flash

Support LPDDR4, DDR4, DDR3L; Quad SPI with XIP

◆ Temperature: consumer electronics (0° C to 95° C Tj); Industrial Controls(-40° C to 105° C Tj)

◆ Operating system: support Linux, Android



## 2.2、 Mainboard Resource:

Hardware Resources	
CPU	NXP i.MX8M Mini processor, Quad ARM® Cortex™-A53+Cortex-M4, 1.8 GHz of i.MX8M, 400MHz of Cortex®-M4
RAM	2GB LPDDR4
Flash	8GB EMMC, ( 16GB EMMC、 32GB EMMC Optional)
Network	1-ch AR8035 Internet chip adopts RGMII supporting adaptability 110M/100M/1000M
	1-ch LAN 7430 port chip, supporting 10M/ 100M/1000M
	Onboard WIFI (AP6236)
Communication	4-ch RS232, 2-ch debug UART
	4-ch USB 2.0, 1-ch USB-OTG
	2-ch CAN 2.0
Display	4-ch MIPI each Display channel' s resolution up to 1920 * 1200
Audio	McASP audio interface; binaural output; MIC audio input
Input	Standrad I2C Capacitive panel
	1-ch CSI camera interface (4-ch)
Expansion Interface	MINI-PCIE interface with SIM socket for 4g module
Memory Interface	1-ch SD card
Expansion Interface	GPIO interface
Other	Reset circuit, Watch dog, RTC, Buzzer, JTAG interface
Power Input	+12V power supply
Software Resource	
Development Tools	Development environment: Virtual Machine VM9.0.2+ubuntu14.04 or Ubuntu 14.04
	Application layer development debug tool
	Cross-compiler
	Common terminal development debugging tool
Image File	ISO of matched operating system
Test Program	Interface using demo test program and test program source code
Source Code	Bootloader, kernel, system source code
Manual	Mainboard User manual, Hardware Manual, Device Manual

Electrical Property	Mechanical Chart	Carrier Board's Structure & Size
	Size	Core Board: 55mm*60mm, 8-layer high precision immersion gold process
		Back Board: 200mm*130mm, 4-layer high precision immersion gold process
	Power Consumption	≤5W (Non-loaded consumption)
	Operation Temperature	-40°C ~ +85°C ( industrial level ), 0°C ~ +85°C ( Consumer Level, According to customers' requirements )
Operation Humidity	5% ~ 95%, Non-Condensing	

### 2.3、SOM Resource:

IAC-IMX8MM adopts 8-layer high precision immersion gold process PC board and high glass transition temperature material with reliable electrical specification and disturbance rejection behaviour. SOM integrates CPU, LPDDR4, eMMC, power management circuits and so on. More than 150 pin from board to board connector apply to IAC-IMX8MM to expand its hardware resource. According to Pin status and multiplex combination of different interface functions, back panel would be designed.

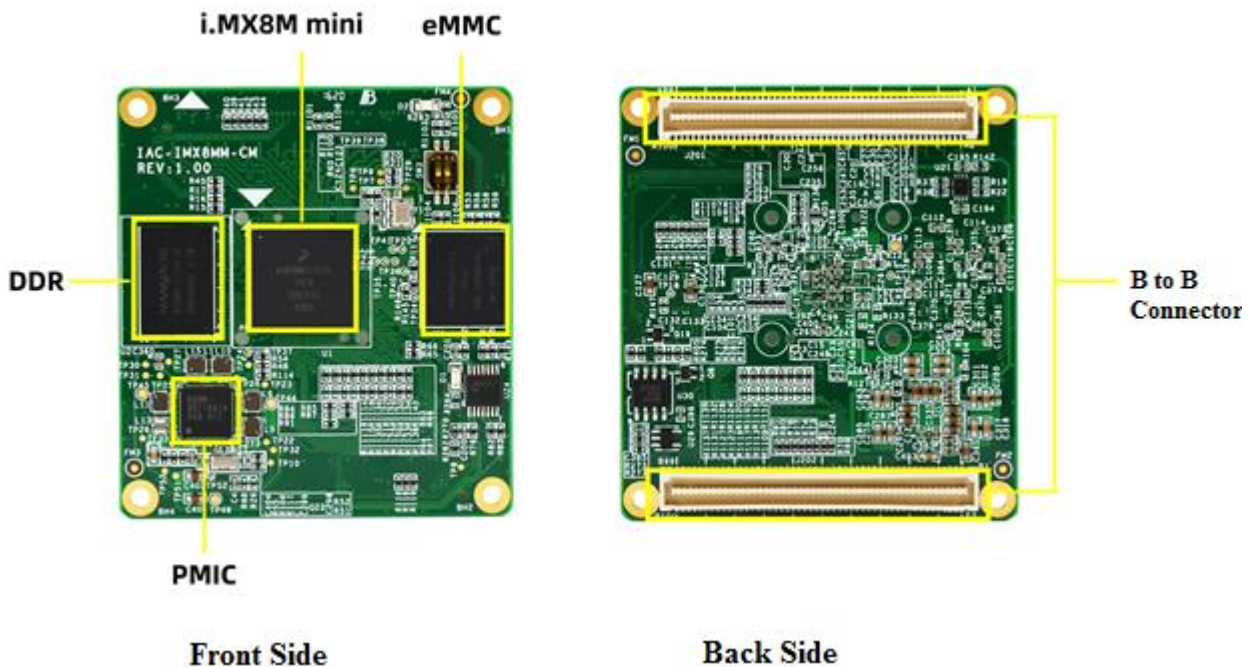


Chart 2

- ◆ Onboard with NXP I.MX8M Mini Processor;
- ◆ Onboard with 2GB LPDDR4,8GB EMMC (Default Setting)
- ◆ SOM adopts 8-layer high precision gold immersion process technology;
- ◆ SOM Size: 55mm\*60mm, suits for various applications.
- ◆ SOM adopts 2X2\*50PIN Board To Board connector to draw out the SOM source.
- ◆ Adopts 5V, onboard with power management chipset; SOM power consumption <2W;
- ◆ Supports Linux4.14.98+QT5.10.1
- ◆ Supports Android 9.0;
- ◆ Interfaces and Pins' definition from the core board see in the Functions on Board part.

### III. Functions on Carrier Board

#### Interface Framework

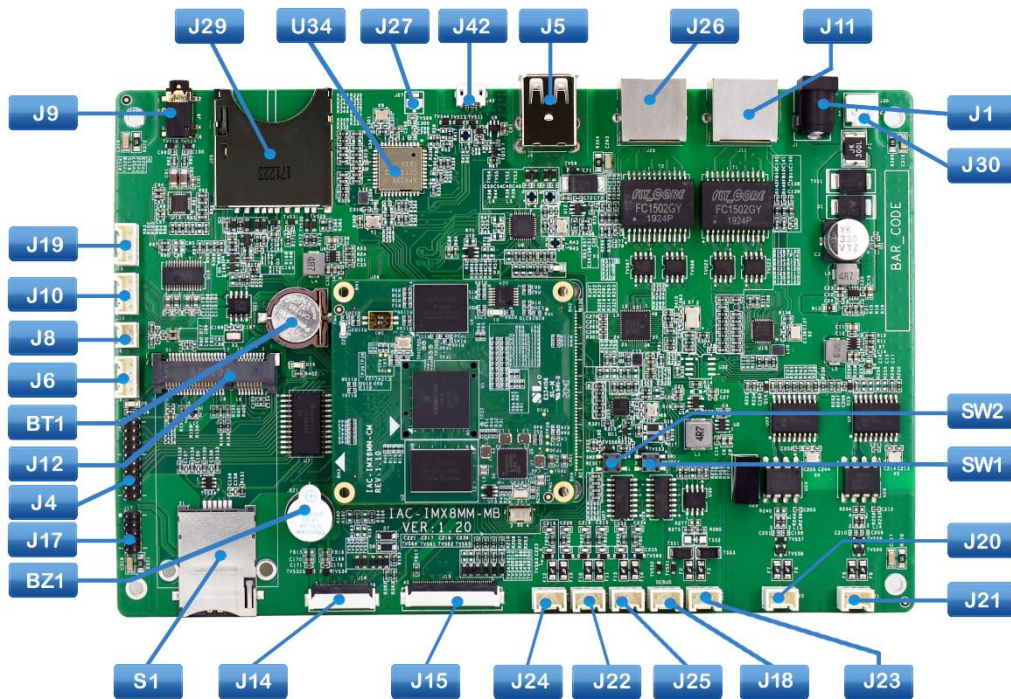


Chart 3

Selectable MIPI-HDMI, MIPI-LVDS, MIPI-MIPI Converter Board, to connect more available displays.



MIPI-HDMI



MIPI-LVDS



MIPI-MIPI

Chart 4

### 3.1. Basic Function Description:

Label	Function
J1	DC 12V Power In
J4	16-ch GPIO
J5	USB2.0
J6	USB2.0
J8	MIC Audio Input
J9	Audio Output
J10	Speaker Output
J11	Gigabit Ethernet
J12	MINI_PCIE
J14	CSI1 Camera (4-Lane CSI)
J15	MIPI & I2C
J17	JTAG (M4 JTAG)



J18	RS232 (I.MX8M Debug UART)
J19	UART4 (M4 Debug UART)
J20	CAN
J21	CAN
J22	RS232 (COM3)
J23	RS485 (COM1)
J24	RS232 (COM2)
J25	RS232(COM4)
J26	Gigabit Ethernet
J27	WIFI-IPEX Antenna
J29	SD Card Socket
J30	DC12V Power Input
J42	USB-OTG
SW1	ON/OFF Button
SW2	Reset Button
BZ1	Buzzer
BT1	Battery for RTC(+3.0V)
S1	SIM Card Socket
U34	WIFI Module (AP6236 )

### 3.2. DIP Switch Setting

SW3: BOOT MODE

SW setting in SOM:

SW1	SW2	BOOT MODE
0	0	Boot From Fuses

0	1	Serial Downloader
1	0	Internal Boot (Development)
1	1	Reserved

### 3.3. Pin Definition:

J28-1: (On SOM Pin)

Signal Name	Pin No.	Pin No.	Signal Name
ECSPI1_SS0	1	2	GND
ECSPI1_SCLK	3	4	DSI_DN0
ECSPI1_MISO	5	6	DSI_DP0
ECSPI1_MOSI	7	8	GND
GND	9	10	DSI_DN1
ECSPI2_SS0	11	12	DSI_DP1
ECSPI2_SCLK	13	14	GND
ECSPI2_MISO	15	16	DSI_CKN
ECSPI2_MOSI	17	18	DSI_CKP
GND	19	20	GND
I2C2_SCL	21	22	DSI_DN2
I2C2_SDA	23	24	DSI_DP2
I2C3_SCL	25	26	GND
I2C3_SDA	27	28	DSI_DN3
I2C4_SCL	29	30	DSI_DP3

I2C4_SDA	31	32	GND
GND	33	34	CSI_DN0
UART2_RXD	35	36	CSI_DP0
UART2_TXD	37	38	GND
UART4_RXD	39	40	CSI_DN1
UART4_TXD	41	42	CSI_DP1
GND	43	44	GND
JTAG_TDO	45	46	CSI_CKN
JTAG_TDI	47	48	CSI_CKP
JTAG_TMS	49	50	GND
JTAG_nTRST	51	52	CSI_DN2
JTAG_TCK	53	54	CSI_DP2
GND	55	56	GND
SD2_DATA0	57	58	CSI_DN3
SD2_DATA1	59	60	CSI_DP3
SD2_DATA2	61	62	GND
SD2_DATA3	63	64	PCIE_RXN
SD2_nRST	65	66	PCIE_RXP
SD2_CLK	67	68	GND
SD2_CMD	69	70	PCIE_TXN
SD2_nCD	71	72	PCIE_TXP
GND	73	74	GND
SAI3_MCLK	75	76	PCIE_CLKN
SAI3_TXFS	77	78	PCIE_CKCP
SAI3_TXC	79	80	GND



SAI3_TXD	81	82	USB1_VBUS
SAI3_RXFS	83	84	USB1_DN
SAI3_RXC	85	86	USB1_DP
SAI3_RXD	87	88	USB1_ID
GND	89	90	GND
QSPIA_nSS0	91	92	USB2_VBUS
QSPIA_SCLK	93	94	USB2_DN
QSPIA_MOSI	95	96	USB2_DP
QSPIA_MISO	97	98	USB2_ID
GND	99	100	GND

J28-2: (On SOM Pin)

Signal Name	Pin No.	Pin No.	Signal Name
VCC_SYS_5V0	1	2	VCC_SYS_5V0
VCC_SYS_5V0	3	4	VCC_SYS_5V0
VCC_SYS_5V0	5	6	VCC_SYS_5V0
VCC_SYS_5V0	7	8	VCC_SYS_5V0
GND	9	10	GND
GND	11	12	GND
GND	13	14	GND
GND	15	16	GND
GND	17	18	GND
GND	19	20	GND
NVCC_ENET	21	22	GND
NVCC_ENET	23	24	GND
ENET_TX_CTL	25	26	REF_CLK_32K

ENET_TXC	27	28	GND
GND	29	30	IO_PWM1_OUT
ENET_TD0	31	32	POR_B
ENET_TD1	33	34	SYS_nRST
ENET_TD2	35	36	ONOFF
ENET_TD3	37	38	USB_HUB_RST
GND	39	40	IO_CAN1_nRST
ENET_RX_CTL	41	42	IO_CAN2_nRST
ENET_RXC	43	44	IO_CAN1_nINT
GND	45	46	IO_CAN2_nINT
ENET_RD0	47	48	GPIO_ENET1_INT
ENET_RD1	49	50	GPIO_TP_INT
ENET_RD2	51	52	GPIO_CSI_PWDN
ENET_RD3	53	54	GPIO_CSI_RST
GND	55	56	QSPIA_DATA3
ENET_MDC	57	58	QSPIA_DATA2
ENET_MDIO	59	60	SAI2_MCLK
GND	61	62	SAI2_RXFS
SD1_CLK	63	64	SAI2_RXC
SD1_CMD	65	66	SAI1_RXFS
GND	67	68	SAI1_RXC
SD1_DATA0	69	70	SAI1_MCLK
SD1_DATA1	71	72	SAI1_TXFS
SD1_DATA2	73	74	SAI1_TXC
SD1_DATA3	75	76	SAI5_RXFS

WL_WAKE_HOST	77	78	SAI5_MCLK
WL_REG_ON	79	80	SAI5_RXC
IO_CLK_REQ	81	82	SAI5_RXD0
GND	83	84	SAI5_RXD1
UART1_RXD	85	86	SAI5_RXD2
UART1_TXD	87	88	SAI5_RXD3
UART1_CTS	89	90	SPDIF_TX
UART1_RTS	91	92	SPDIF_RX
SAI2_RXD	93	94	SPDIF_EXT_CLK
SAI2_TXD	95	96	BT_REG_ON
SAI2_TXC	97	98	BT_WAKE_DEV
SAI2_TXFS	99	100	BT_WAKE_HOST

#### J4: GPIO Interface

Signal Name	Pin No.	Pin No.	Signal Name
EXP_IO1	1	2	EXP_IO9
EXP_IO2	3	4	EXP_IO10
EXP_IO3	5	6	EXP_IO11
EXP_IO4	7	8	EXP_IO12
EXP_IO5	9	10	EXP_IO13
EXP_IO6	11	12	EXP_IO14
EXP_IO7	13	14	EXP_IO15
EXP_IO8	15	16	EXP_IO16
I2C4_SDA	17	18	QSPIA_DATA3
GND	19	20	GND

J6: USB

Pin No.	Signal Name
1	VCC_USB3(5V0)
2	USB_DN3
3	USB_DP3
4	GND

J8: MIC Audio Input

Pin No.	Signal Name
1	MIC-
2	MIC+

J10: Audio Output (Amplifier Output)

Pin No.	Signal Name
1	SPKPL
2	SPKNL
3	SPKNR
4	SPKPR

J12: MINI-PCIE:

Signal Name	Pin No.	Pin No.	Signal Name
NC	1	2	VCC_PCIE_3V3
NC	3	4	GND
NC	5	6	NC
NC	7	8	SIM_VDD
GND	9	10	SM_DATA

NC	11	12	SIM_CLK
NC	13	14	SIM_RST
GND	15	16	NC
NC	17	18	GND
NC	19	20	PCIE_nDISEN
GND	21	22	PCIE_nRST
NC	23	24	VCC_PCIE_3V3
NC	25	26	GND
GND	27	28	NC
GND	29	30	NC
NC	31	32	NC
NC	33	34	GND
GND	35	36	PCIE_USB_DN
GND	37	38	PCIE_USB_DP
VCC_PCIE_3V3	39	40	GND
VCC_PCIE_3V3	41	42	VCC_PCIE_3V3
GND	43	44	NC
NC	45	46	NC
NC	47	48	NC
NC	49	50	GND
NC	51	52	VCC_PCIE_3V3

J14: CSI(4-Lane CSI):

Pin No.	Signal Name
1	VCC_DVP_5V0

2	GND
3	VCC_DVP_3V3
4	VCC_DVP_3V3
5	GND
6	CSI1_CKN
7	CSI1_CKP
8	GND
9	CSI1_DN0
10	CSI1_DP0
11	GND
12	CSI1_DN1
13	CSI1_DP1
14	GND
15	CSI1_DN2
16	CSI1_DP2
17	GND
18	CSI1_DN3
19	CSI1_DP3
20	GND
21	CSI1_I2C_SDA
22	CSI1_I2C_SCL
23	CSI1_PWDN
24	CS1_RST
25	GND
26	CSI1_PWR_EN

J15: MIPI (4-Lane) & I2C Touch Panel

Selectable to connect different converter board, to externally connect HDMI,LVDS,MIPI monitors.

Pin No.	Signal Name
1	TP_I2C_SDA
2	TP_I2C_SCL
3	TP_RST
4	TP_INT
5	LED_BL_EN
6	VCC_IO_5V0
7	VCC_IO_5V0
8	VCC_IO_5V0
9	VCC_IO_5V0
10	GND
11	GND
12	GND
13	DSI_I2C_SDA
14	LCD_MIPI_RST
15	DSI_I2C_SCL
16	GND
17	LCD_MIPI_3N
18	LCD_MIPI_3P
19	GND
20	LCD_MIPI_0N
21	LCD_MIPI_0P
22	GND
23	LCD_MIPI_CLKN



24	LCD_MIPI_CLKP
25	GND
26	LCD_MIPI_1N
27	LCD_MIPI_1P
28	GND
29	LCD_MIPI_2N
30	LCD_MIPI_2P
31	GND
32	PWM1_OUT
33	GND
34	GND
35	GND
36	NC
37	VCC_EXT_12V0
38	VCC_EXT_12V0
39	VCC_EXT_12V0
40	VCC_EXT_12V0

J17: JTAG

Signal Name	Pin No.	Pin No.	Signal Name
VCC(3V3)	1	2	TMS
GND	3	4	TCK
GND	5	6	TDO
GND	7	8	TDI
GND	9	10	nRST

J18: UART2(IMX8M Debug UART)

PIN No.	Signal Name
1	UART2_TXD
2	UART2_RXD
3	GND

J19: UART4(M4 Debug UART)

PIN No.	Signal Name
1	UART4_TXD
2	UART4_RXD
3	GND

J20: CAN

PIN No.	Signal Name
1	CAN3H
2	CAN3L
3	GND

J21: CAN

PIN No.	Signal Name
1	CAN4H
2	CAN4L
3	GND

J22: RS232(COM3)

PIN No.	Signal Name
1	COM3_TXD
2	COM3_RXD
3	GND

## J23: RS232 (COM1)

PIN No.	Signal Name
1	COM1_TXD
2	COM1_RXD
3	GND

## J24: RS232 (COM2)

PIN No.	Signal Name
1	COM2_TXD
2	COM2_RXD
3	GND

## J25: RS232(COM4)

PIN No.	Signal Name
1	COM4_TXD
2	COM4_RXD
3	GND

## J30: DC12V Power In

PIN No.	Signal Name
1	12V
2	GND

## IV. Structure & Size:

Unit of measurement: mm, if needs the receptacle's size, please email us : [supports@qiyangtech.com](mailto:supports@qiyangtech.com);

Any question, please send E-mail : [supports@qiyangtech.com](mailto:supports@qiyangtech.com)

Sales E-mail : [trade@qiyangtech.com](mailto:trade@qiyangtech.com) [sales@qiyangtech.com](mailto:sales@qiyangtech.com)

Website: <http://www.qiytech.com>

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### 4. 1. SOM Dimension

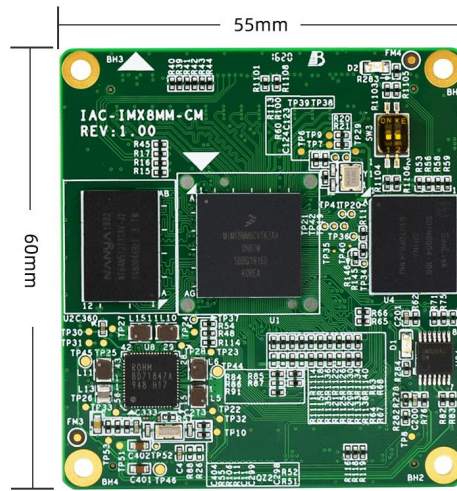


Chart 5

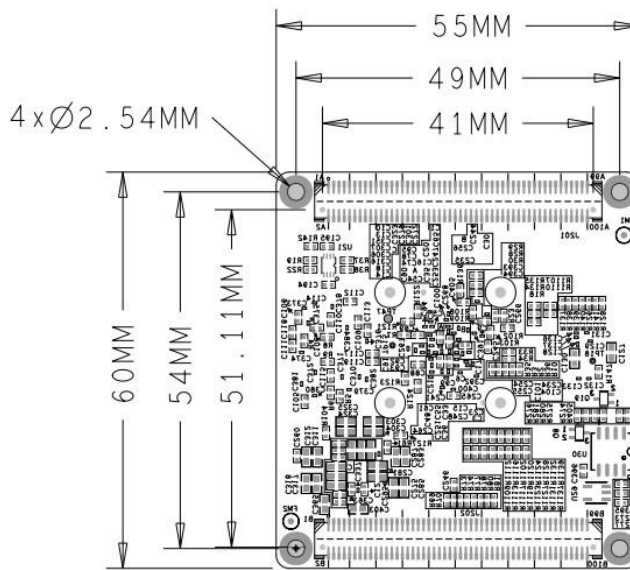


Chart 6

## 4.2. Carrier Board Dimension:

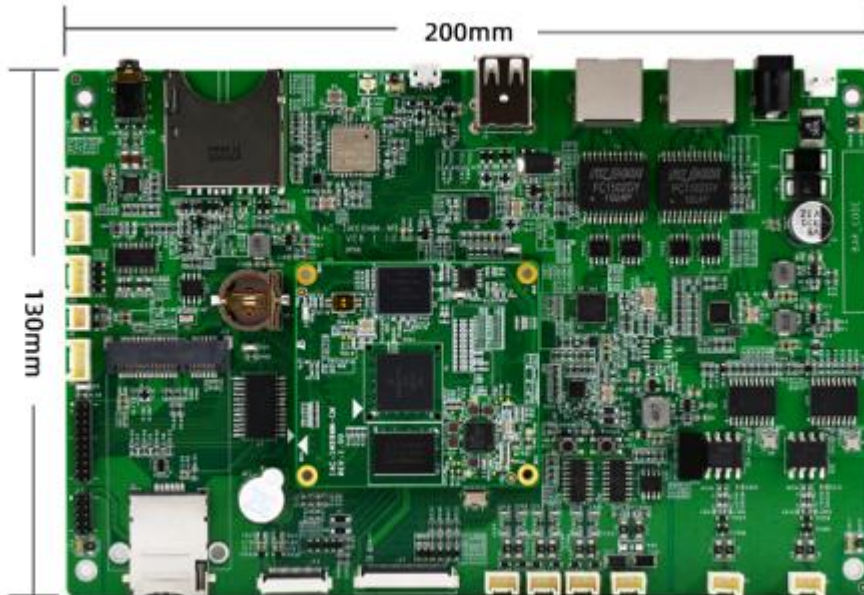


Chart 7

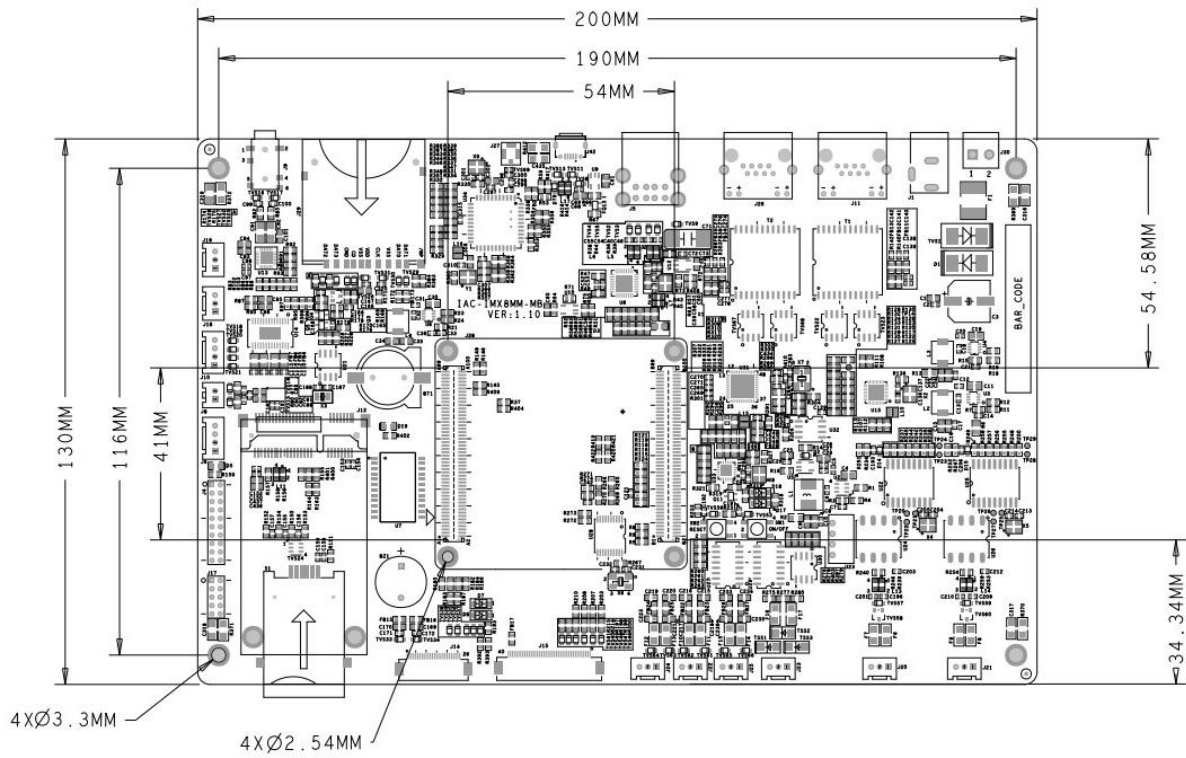


Chart 8



## V. Connection Picture

Take a notice about the location of the SOM

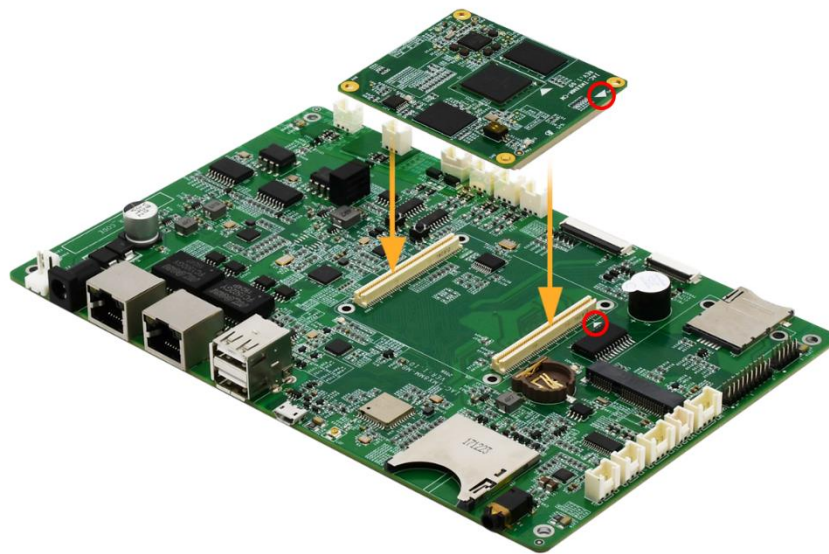
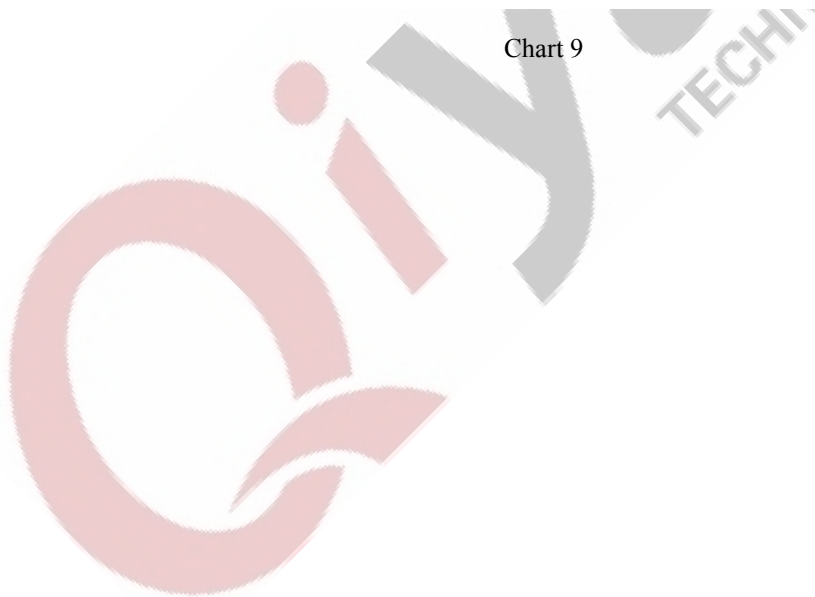


Chart 9





## VI. Electrical Property

Items	Parameters
Operation Temp.	-40°C ~ +85°C
Storage Temp.	-40°C ~ +85°C
Humidity	5%~95%, non-condensing
SOM Dimension	55mm*60mm,8-layer high precision gold immersion process technology
Carrier Board Dimension	200mm*130mm,4-layer high precision gold immersion process technology.
Power Consumption	≤2W
Whole Board Power Consumption	≤5W, no workload
Power	DC12V/2.5A

## VII. Software Description:

IAC-IMX8MM-KIT provides software support, mainly including Linux/Android.

*IAC-IMX8MM-KIT Linux User Manual* introduces how to establish and use the development environment in Linux OS specifically. If you need details, please reference that manual.

*IAC-IMX8MM-KIT Android User Manual* introduces how to establish and use the development environment in Android OS particularly. If you need details, please reference that manual.

## VIII. Remark

1. Before connecting to LCD, please confirm LCD power specification.
2. Please use the original connecting accessories to avoid damaging the main board.
3. We ensure offering communication technology support through E-mail, telephone for lifelong technical support service.
4. We ensure offering 6-months repair service for free, if malfunction occurs in warranty because of quality problem. Under that circumstance, please contact our retailer or our company with purchase receipt within warranty period, we are willing to repair or replace.
5. Under these circumstances, we do not offer repair for free:
  - Over warranty time;
  - Do not attach purchase receipt;
  - Liquid inlet, damp or mold;
  - Malfunction and damage is not due to product quality but drops, intense sharking, arbitrarily modify, disoperation after purchase;
  - Damage of force majeure.
6. We reserve intellectual property for the software and hardware technical data of **IAC-IMX8MM-KIT**; users can only use them for teaching, testing, researching. Shall not be engaged in any commercial purpose. Shall not distribute them on the Internet. Shall not intercept, modify them to tamper copyright.
7. We accept batch order; we can offer technical support and service.

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